

Welcome to E-XFL.COM

What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Obsolete
Core Processor	HC08
Core Size	8-Bit
Speed	8MHz
Connectivity	SCI
Peripherals	LED, LVD, POR, PWM
Number of I/O	23
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 13x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc908jl8mdwe

2.4 Random-Access Memory (RAM)

Addresses \$0060 through \$015F are RAM locations. The location of the stack RAM is programmable. The 16-bit stack pointer allows the stack to be anywhere in the 64-Kbyte memory space.

NOTE

For correct operation, the stack pointer must point only to RAM locations.

Within page zero are 160 bytes of RAM. Because the location of the stack RAM is programmable, all page zero RAM locations can be used for I/O control and user data or code. When the stack pointer is moved from its reset location at \$00FF, direct addressing mode instructions can access efficiently all page zero RAM locations. Page zero RAM, therefore, provides ideal locations for frequently accessed global variables.

Before processing an interrupt, the CPU uses five bytes of the stack to save the contents of the CPU registers.

NOTE

For M6805 compatibility, the H register is not stacked.

During a subroutine call, the CPU uses two bytes of the stack to store the return address. The stack pointer decrements during pushes and increments during pulls.

NOTE

Be careful when using nested subroutines. The CPU may overwrite data in the RAM during a subroutine or during the interrupt stacking operation.

2.5 FLASH Memory

This sub-section describes the operation of the embedded FLASH memory. The FLASH memory can be read, programmed, and erased from a single external supply. The program and erase operations are enabled through the use of an internal charge pump.

2.6 Functional Description

The FLASH memory consists of an array of 8,192 bytes for user memory plus a block of 36 bytes for user interrupt vectors. *An erased bit reads as logic 1 and a programmed bit reads as a logic 0.* The FLASH memory page size is defined as 64 bytes, and is the minimum size that can be erased in a page erase operation. Program and erase operations are facilitated through control bits in FLASH control register (FLCR).

The address ranges for the FLASH memory are:

- \$DC00–\$FBFF; user memory; 12,288 bytes
- \$FFDC–\$FFFF; user interrupt vectors; 36 bytes

Programming tools are available from Freescale. Contact your local Freescale representative for more information.

NOTE

A security feature prevents viewing of the FLASH contents.⁽¹⁾

1. No security feature is absolutely secure. However, Motorola's strategy is to make reading or copying the FLASH difficult for unauthorized users.

Memory

8. Wait for time, t_{prog} (30 μ s).
9. Repeat steps 7 and 8 until all bytes within the row are programmed.
10. Clear the PGM bit.
11. Wait for time, t_{nvh} (5 μ s).
12. Clear the HVEN bit.
13. After time, t_{rcv} (1 μ s), the memory can be accessed in read mode again.

This program sequence is repeated throughout the memory until all data is programmed.

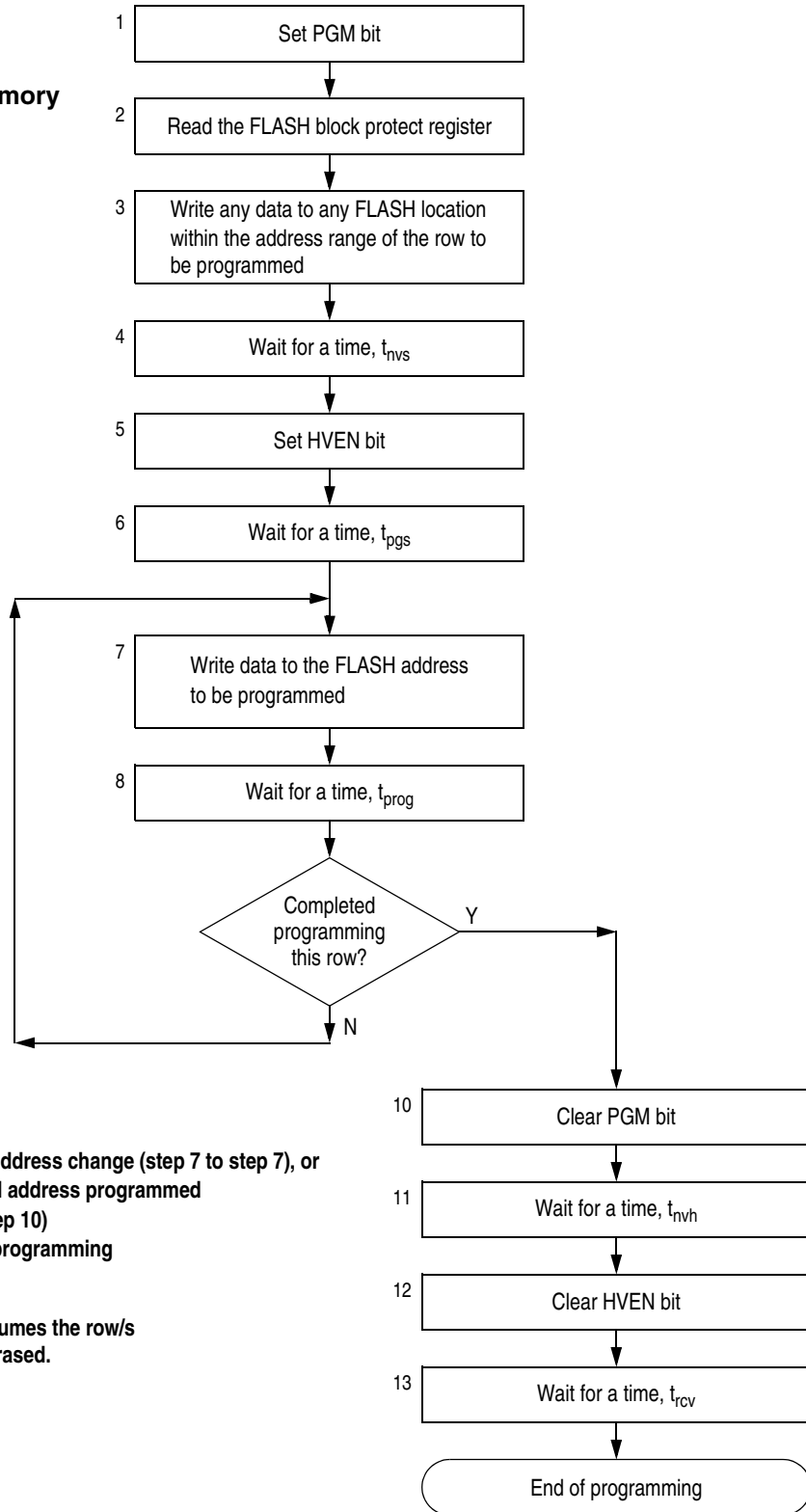
NOTE

The time between each FLASH address change (step 7 to step 7), or the time between the last FLASH addressed programmed to clearing the PGM bit (step 7 to step 10), must not exceed the maximum programming time, $t_{prog\ max}$.

NOTE

Programming and erasing of FLASH locations cannot be performed by code being executed from the FLASH memory. While these operations must be performed in the order shown, other unrelated operations may occur between the steps.

Algorithm for programming a row (32 bytes) of FLASH memory



NOTE:

The time between each FLASH address change (step 7 to step 7), or the time between the last FLASH address programmed to clearing PGM bit (step 7 to step 10) must not exceed the maximum programming time, $t_{prog\ max}$.

This row program algorithm assumes the row/s to be programmed are initially erased.

Figure 2-4. FLASH Programming Flowchart

3.3 Configuration Register 1 (CONFIG1)

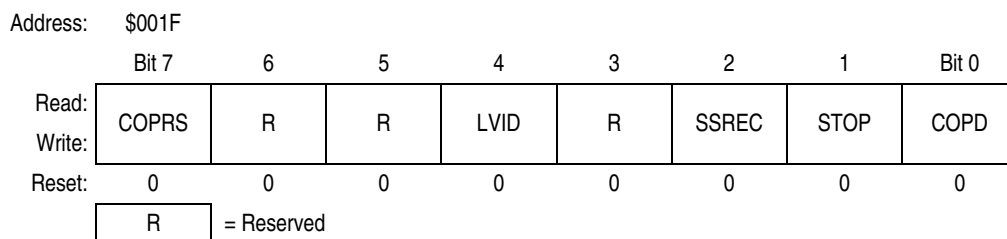


Figure 3-1. Configuration Register 1 (CONFIG1)

COPRS — COP Rate Select Bit

COPRS selects the COP time-out period. Reset clears COPRS.

(See [Chapter 14 Computer Operating Properly \(COP\)](#).)

1 = COP timeout period is $(2^{13} - 2^4)$ ICLK cycles

0 = COP timeout period is $(2^{18} - 2^4)$ ICLK cycles

LVID — Low Voltage Inhibit Disable Bit

LVID disables the LVI module. Reset clears LVID.

(See [Chapter 15 Low Voltage Inhibit \(LVI\)](#).)

1 = Low voltage inhibit disabled

0 = Low voltage inhibit enabled

SSREC — Short Stop Recovery Bit

SSREC enables the CPU to exit stop mode with a delay of

32 ICLK cycles instead of a 4096 ICLK cycle delay.

1 = Stop mode recovery after 32 ICLK cycles

0 = Stop mode recovery after 4096 ICLK cycles

NOTE

*Exiting stop mode by pulling reset will result in the long stop recovery.
If using an external crystal, do not set the SSREC bit.*

STOP — STOP Instruction Enable Bit

STOP enables the STOP instruction.

1 = STOP instruction enabled

0 = STOP instruction treated as illegal opcode

COPD — COP Disable Bit

COPD disables the COP module. Reset clears COPD.

(See [Chapter 14 Computer Operating Properly \(COP\)](#).)

1 = COP module disabled

0 = COP module enabled

Configuration and Mask Option Registers (CONFIG & MOR)

Bits 6–0 — Should be left as logic 1's.

NOTE

When Crystal oscillator is selected, the OSC2/RCCLK/PTA6/KBI6 pin is used as OSC2; other functions such as PTA6/KBI6 will not be available.

Table 4-1. Instruction Set Summary

Source Form	Operation	Description	Effect on CCR						Address Mode	Opcode	Operand	Cycles
			V	H	I	N	Z	C				
DBNZ <i>opr,rel</i> DBNZ <i>rel</i> DBNZX <i>rel</i> DBNZ <i>opr,X,rel</i> DBNZ <i>X,rel</i> DBNZ <i>opr,SP,rel</i>	Decrement and Branch if Not Zero	$A \leftarrow (A) - 1$ or $M \leftarrow (M) - 1$ or $X \leftarrow (X) - 1$ $PC \leftarrow (PC) + 3 + rel ? (result) \neq 0$ $PC \leftarrow (PC) + 2 + rel ? (result) \neq 0$ $PC \leftarrow (PC) + 2 + rel ? (result) \neq 0$ $PC \leftarrow (PC) + 3 + rel ? (result) \neq 0$ $PC \leftarrow (PC) + 2 + rel ? (result) \neq 0$ $PC \leftarrow (PC) + 4 + rel ? (result) \neq 0$	-	-	-	-	-	-	DIR INH INH IX1 IX SP1	3B 4B 5B 6B 7B 9E6B	dd rr rr rr ff rr rr ff rr	5 3 3 5 4 6
DEC <i>opr</i> DECA DECX DEC <i>opr,X</i> DEC <i>,X</i> DEC <i>opr,SP</i>	Decrement	$M \leftarrow (M) - 1$ $A \leftarrow (A) - 1$ $X \leftarrow (X) - 1$ $M \leftarrow (M) - 1$ $M \leftarrow (M) - 1$ $M \leftarrow (M) - 1$	⚡	-	-	⚡	⚡	-	DIR INH INH IX1 IX SP1	3A 4A 5A 6A 7A 9E6A	dd ff ff	4 1 1 4 3 5
DIV	Divide	$A \leftarrow (H:A)/(X)$ $H \leftarrow \text{Remainder}$	-	-	-	-	⚡	⚡	INH	52		7
EOR # <i>opr</i> EOR <i>opr</i> EOR <i>opr</i> EOR <i>opr,X</i> EOR <i>opr,X</i> EOR <i>,X</i> EOR <i>opr,SP</i> EOR <i>opr,SP</i>	Exclusive OR M with A	$A \leftarrow (A \oplus M)$	0	-	-	⚡	⚡	-	IMM DIR EXT IX2 IX1 IX SP1 SP2	A8 B8 C8 D8 E8 F8 9EE8 9ED8	ii dd hh ll ee ff ff ff ff ee ff	2 3 4 4 3 2 4 5
INC <i>opr</i> INCA INCX INC <i>opr,X</i> INC <i>,X</i> INC <i>opr,SP</i>	Increment	$M \leftarrow (M) + 1$ $A \leftarrow (A) + 1$ $X \leftarrow (X) + 1$ $M \leftarrow (M) + 1$ $M \leftarrow (M) + 1$ $M \leftarrow (M) + 1$	⚡	-	-	⚡	⚡	-	DIR INH INH IX1 IX SP1	3C 4C 5C 6C 7C 9E6C	dd ff ff	4 1 1 4 3 5
JMP <i>opr</i> JMP <i>opr</i> JMP <i>opr,X</i> JMP <i>opr,X</i> JMP <i>,X</i>	Jump	$PC \leftarrow \text{Jump Address}$	-	-	-	-	-	-	DIR EXT IX2 IX1 IX	BC CC DC EC FC	dd hh ll ee ff ff	2 3 4 3 2
JSR <i>opr</i> JSR <i>opr</i> JSR <i>opr,X</i> JSR <i>opr,X</i> JSR <i>,X</i>	Jump to Subroutine	$PC \leftarrow (PC) + n (n = 1, 2, \text{ or } 3)$ Push (PCL); $SP \leftarrow (SP) - 1$ Push (PCH); $SP \leftarrow (SP) - 1$ $PC \leftarrow \text{Unconditional Address}$	-	-	-	-	-	-	DIR EXT IX2 IX1 IX	BD CD DD ED FD	dd hh ll ee ff ff	4 5 6 5 4
LDA # <i>opr</i> LDA <i>opr</i> LDA <i>opr</i> LDA <i>opr,X</i> LDA <i>opr,X</i> LDA <i>,X</i> LDA <i>opr,SP</i> LDA <i>opr,SP</i>	Load A from M	$A \leftarrow (M)$	0	-	-	⚡	⚡	-	IMM DIR EXT IX2 IX1 IX SP1 SP2	A6 B6 C6 D6 E6 F6 9EE6 9ED6	ii dd hh ll ee ff ff ff ff ee ff	2 3 4 4 3 2 4 5
LDHX # <i>opr</i> LDHX <i>opr</i>	Load H:X from M	$H:X \leftarrow (M:M + 1)$	0	-	-	⚡	⚡	-	IMM DIR	45 55	ii jj dd	3 4

Table 4-1. Instruction Set Summary

Source Form	Operation	Description	Effect on CCR						Address Mode	Opcode	Operand	Cycles
			V	H	I	N	Z	C				
PULH	Pull H from Stack	$SP \leftarrow (SP + 1)$; Pull (H)	-	-	-	-	-	-	INH	8A		2
PULX	Pull X from Stack	$SP \leftarrow (SP + 1)$; Pull (X)	-	-	-	-	-	-	INH	88		2
ROL <i>opr</i> ROLA ROLX ROL <i>opr,X</i> ROL ,X ROL <i>opr,SP</i>	Rotate Left through Carry		↕	-	-	↕	↕	↕	DIR INH INH IX1 IX SP1	39 49 59 69 79 9E69	dd ff ff	4 1 1 4 3 5
ROR <i>opr</i> RORA RORX ROR <i>opr,X</i> ROR ,X ROR <i>opr,SP</i>	Rotate Right through Carry		↕	-	-	↕	↕	↕	DIR INH INH IX1 IX SP1	36 46 56 66 76 9E66	dd ff ff	4 1 1 4 3 5
RSP	Reset Stack Pointer	$SP \leftarrow \$FF$	-	-	-	-	-	-	INH	9C		1
RTI	Return from Interrupt	$SP \leftarrow (SP + 1)$; Pull (CCR) $SP \leftarrow (SP + 1)$; Pull (A) $SP \leftarrow (SP + 1)$; Pull (X) $SP \leftarrow (SP + 1)$; Pull (PCH) $SP \leftarrow (SP + 1)$; Pull (PCL)	↕	↕	↕	↕	↕	↕	INH	80		7
RTS	Return from Subroutine	$SP \leftarrow SP + 1$; Pull (PCH) $SP \leftarrow SP + 1$; Pull (PCL)	-	-	-	-	-	-	INH	81		4
SBC # <i>opr</i> SBC <i>opr</i> SBC <i>opr</i> SBC <i>opr,X</i> SBC <i>opr,X</i> SBC ,X SBC <i>opr,SP</i> SBC <i>opr,SP</i>	Subtract with Carry	$A \leftarrow (A) - (M) - (C)$	↕	-	-	↕	↕	↕	IMM DIR EXT IX2 IX1 IX SP1 SP2	A2 B2 C2 D2 E2 F2 9EE2 9ED2	ii dd hh ll ee ff ff ff ff ee ff	2 3 4 4 3 2 4 5
SEC	Set Carry Bit	$C \leftarrow 1$	-	-	-	-	-	1	INH	99		1
SEI	Set Interrupt Mask	$I \leftarrow 1$	-	-	1	-	-	-	INH	9B		2
STA <i>opr</i> STA <i>opr</i> STA <i>opr,X</i> STA <i>opr,X</i> STA ,X STA <i>opr,SP</i> STA <i>opr,SP</i>	Store A in M	$M \leftarrow (A)$	0	-	-	↕	↕	-	DIR EXT IX2 IX1 IX SP1 SP2	B7 C7 D7 E7 F7 9EE7 9ED7	dd hh ll ee ff ff ff ff ee ff	3 4 4 3 2 4 5
STHX <i>opr</i>	Store H:X in M	$(M:M + 1) \leftarrow (H:X)$	0	-	-	↕	↕	-	DIR	35	dd	4
STOP	Enable \overline{IRQ} Pin; Stop Oscillator	$I \leftarrow 0$; Stop Oscillator	-	-	0	-	-	-	INH	8E		1

5.5.2.2 Interrupt Status Register 2

Address: \$FE05

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	IF14	IF13	IF12	IF11	0	0	IF8	IF7
Write:	R	R	R	R	R	R	R	R
Reset:	0	0	0	0	0	0	0	0

R = Reserved

Figure 5-13. Interrupt Status Register 2 (INT2)

IF7, IF8, IF11 to F14 — Interrupt Flags

This flag indicates the presence of interrupt requests from the sources shown in [Table 5-3](#).

- 1 = Interrupt request present
- 0 = No interrupt request present

Bit 2 and 3 — Always read 0

5.5.2.3 Interrupt Status Register 3

Address: \$FE06

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	0	0	0	0	0	0	0	IF15
Write:	R	R	R	R	R	R	R	R
Reset:	0	0	0	0	0	0	0	0

R = Reserved

Figure 5-14. Interrupt Status Register 3 (INT3)

IF15 — Interrupt Flags

These flags indicate the presence of interrupt requests from the sources shown in [Table 5-3](#).

- 1 = Interrupt request present
- 0 = No interrupt request present

Bit 1 to 7 — Always read 0

5.5.3 Reset

All reset sources always have equal and highest priority and cannot be arbitrated.

5.5.4 Break Interrupts

The break module can stop normal program flow at a software-programmable break point by asserting its break interrupt output. (See [Chapter 16 Break Module \(BREAK\)](#).) The SIM puts the CPU into the break state by forcing it to the SWI vector location. Refer to the break interrupt subsection of each module to see how each module is affected by the break state.

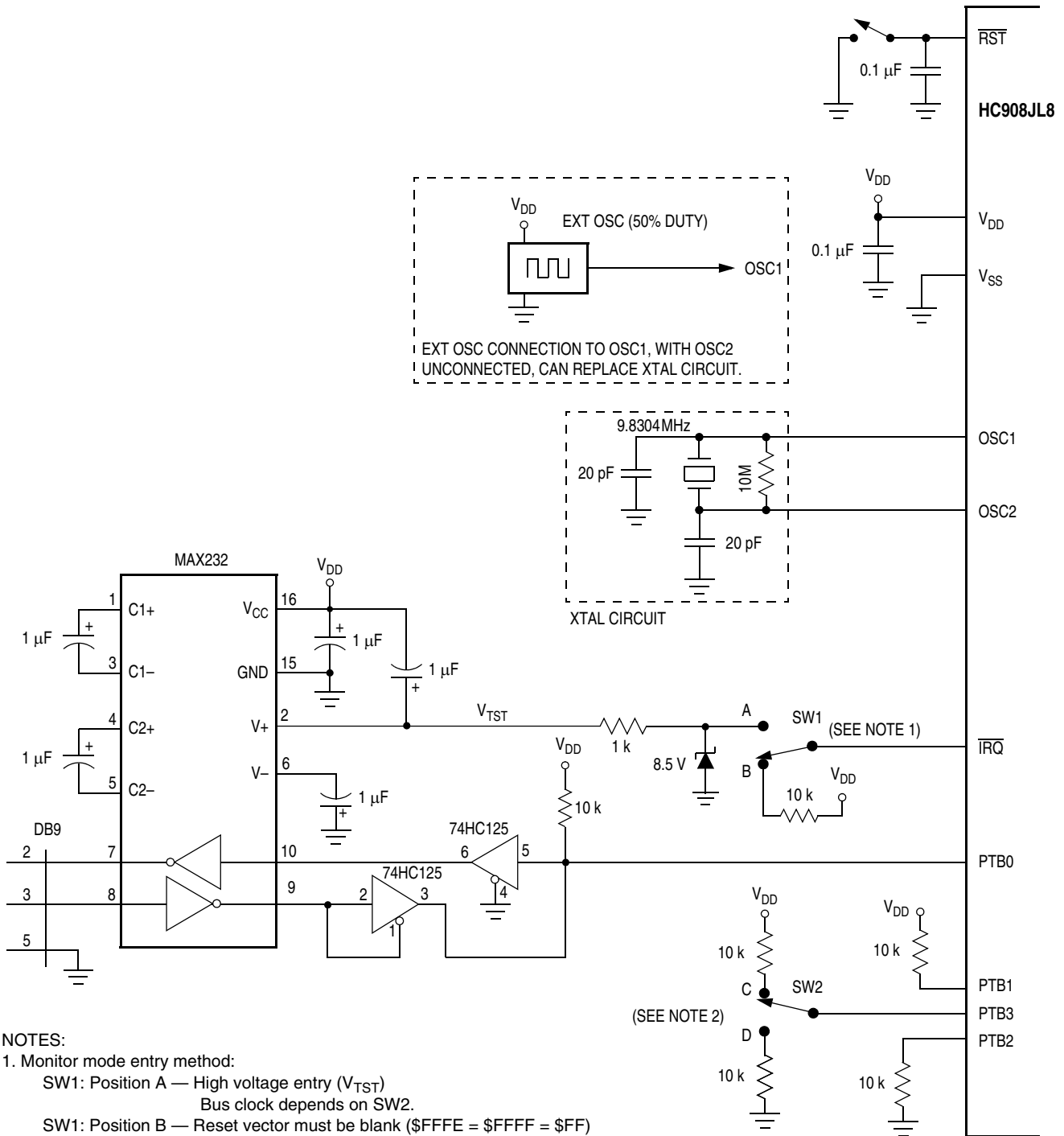


Figure 7-1. Monitor Mode Circuit

Monitor ROM (MON)

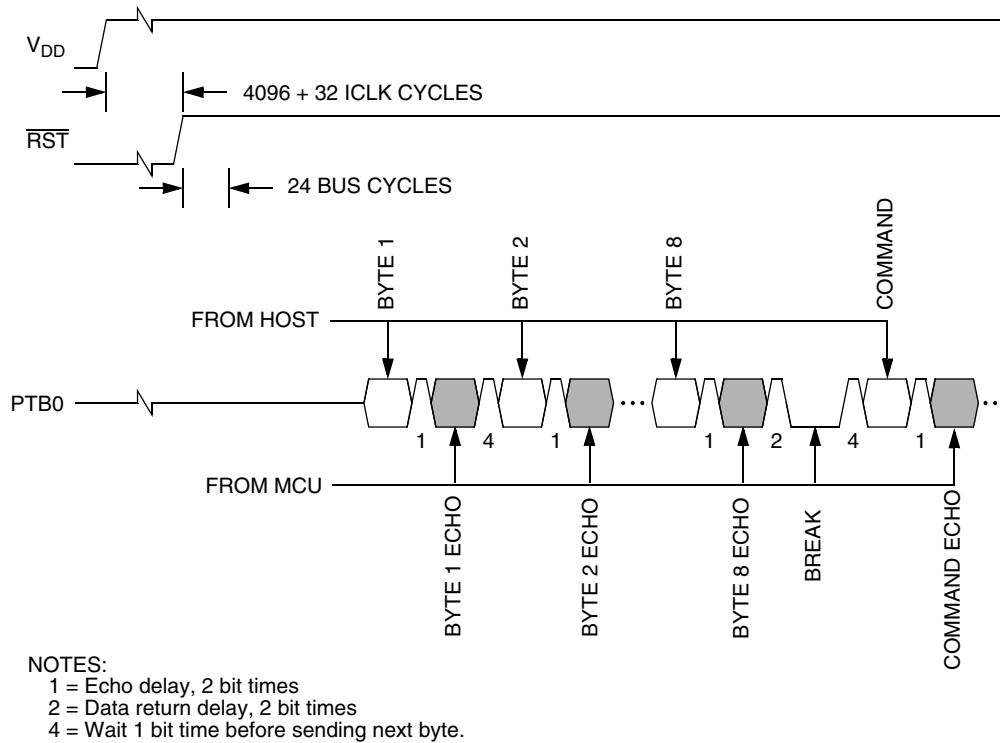


Figure 7-7. Monitor Mode Entry Timing

Upon power-on reset, if the received bytes of the security code do not match the data at locations \$FFF6–\$FFFD, the host fails to bypass the security feature. The MCU remains in monitor mode, but reading a FLASH location returns an invalid value and trying to execute code from FLASH causes an illegal address reset. After receiving the eight security bytes from the host, the MCU transmits a break character, signifying that it is ready to receive a command.

NOTE

The MCU does not transmit a break character until after the host sends the eight security bytes.

To determine whether the security code entered is correct, check to see if bit 6 of RAM address \$60 is set. If it is, then the correct security code has been entered and FLASH can be accessed.

If the security sequence fails, the device should be reset by a power-on reset and brought up in monitor mode to attempt another entry. After failing the security sequence, the FLASH module can also be mass erased by executing an erase routine that was downloaded into internal RAM. The mass erase operation clears the security code locations so that all eight security bytes become \$FF (blank).

7.5 ROM-Resident Routines

Eight routines stored in the monitor ROM area (thus ROM-resident) are provided for FLASH memory manipulation. Six of the eight routines are intended to simplify FLASH program, erase, and load operations. The other two routines are intended to simplify the use of the FLASH memory as EEPROM. [Table 7-10](#) shows a summary of the ROM-resident routines.

Monitor ROM (MON)

The control and data bytes are described below.

- **Bus speed** — This one byte indicates the operating bus speed of the MCU. The value of this byte should be equal to 4 times the bus speed, and should not be set to less than 4 (i.e. minimum bus speed is 1 MHz).
- **Data size** — This one byte indicates the number of bytes in the data array that are to be manipulated. The maximum data array size is 128. Routines EE_WRITE and EE_READ are restricted to manipulate a data array between 2 to 15 bytes. Whereas routines ERARNGE and MON_ERARNGE do not manipulate a data array, thus, this data size byte has no meaning.
- **Start address** — These two bytes, high byte followed by low byte, indicate the start address of the FLASH memory to be manipulated.
- **Data array** — This data array contains data that are to be manipulated. Data in this array are programmed to FLASH memory by the programming routines: PRGRNGE, MON_PRGRNGE, EE_WRITE. For the read routines: LDRNGE, MON_LDRNGE, and EE_READ, data is read from FLASH and stored in this array.

7.5.1 PRGRNGE

PRGRNGE is used to program a range of FLASH locations with data loaded into the data array.

Table 7-11. PRGRNGE Routine

Routine Name	PRGRNGE
Routine Description	Program a range of locations
Calling Address	\$FC06
Stack Used	15 bytes
Data Block Format	Bus speed (BUS_SPD) Data size (DATASIZE) Start address high (ADDRH) Start address (ADDRL) Data 1 (DATA1) : Data N (DATAN)

The start location of the FLASH to be programmed is specified by the address ADDRH:ADDRL and the number of bytes from this location is specified by DATASIZE. The maximum number of bytes that can be programmed in one routine call is 128 bytes (max. DATASIZE is 128).

ADDRH:ADDRL do not need to be at a page boundary, the routine handles any boundary misalignment during programming. A check to see that all bytes in the specified range are erased is not performed by this routine prior programming. Nor does this routine do a verification after programming, so there is no return confirmation that programming was successful. User must assure that the range specified is first erased.

The coding example below is to program 32 bytes of data starting at FLASH location \$EF00, with a bus speed of 4.9152 MHz. The coding assumes the data block is already loaded in RAM, with the address pointer, FILE_PTR, pointing to the first byte of the data block.

7.5.8 EE_READ

EE_READ is used to load the data array in RAM with a set of data from FLASH.

Table 7-18. EE_READ Routine

Routine Name	EE_READ
Routine Description	Emulated EEPROM read. Data size ranges from 2 to 15 bytes at a time.
Calling Address	\$FDD0
Stack Used	16 bytes
Data Block Format	Bus speed (BUS_SPD) Data size (DATASIZE) Starting address (ADDRH) ⁽¹⁾ Starting address (ADDRL) ⁽¹⁾ Data 1 : Data N

1. The start address must be a page boundary start address: \$xx00, \$xx40, \$xx80, or \$00C0.

The EE_READ routine reads data stored by the EE_WRITE routine. An EE_READ call will retrieve the last data written to a FLASH page and loaded into the data array in RAM. Same as EE_WRITE, the data size indicated by DATASIZE is 2 to 15, and the start address ADDRH:ADDRL must be the FLASH page boundary address.

The coding example below uses the data stored by the EE_WRITE coding example (see [7.5.7 EE_WRITE](#)). It loads the 15-byte data set stored in the \$EF00–\$EE7F page to the data array in RAM. The initialization subroutine is the same as the coding example for EE_WRITE (see [7.5.7 EE_WRITE](#)).

```
EE_READ      EQU      $FDD0
```

```
MAIN:
```

```
    BSR      INITIALIZATION
    :
    :
    LDHX    FILE_PTR
    JSR     EE_READ
    :
```

NOTE

The EE_READ routine is unable to check for incorrect data blocks, such as the FLASH page boundary address and data size. It is the responsibility of the user to ensure the starting address indicated in the data block is at the FLASH page boundary and the data size is 2 to 15. If the FLASH page is programmed with a data array with a different size, the EE_READ call will be ignored.

9.8 I/O Registers

These I/O registers control and monitor SCI operation:

- SCI control register 1 (SCC1)
- SCI control register 2 (SCC2)
- SCI control register 3 (SCC3)
- SCI status register 1 (SCS1)
- SCI status register 2 (SCS2)
- SCI data register (SCDR)
- SCI baud rate register (SCBR)

9.8.1 SCI Control Register 1

SCI control register 1:

- Enables loop mode operation
- Enables the SCI
- Controls output polarity
- Controls character length
- Controls SCI wakeup method
- Controls idle character detection
- Enables parity function
- Controls parity type

Address: \$0013

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	LOOPS	ENSCI	TXINV	M	WAKE	ILTY	PEN	PTY
Write:								
Reset:	0	0	0	0	0	0	0	0

Figure 9-9. SCI Control Register 1 (SCC1)

LOOPS — Loop Mode Select Bit

This read/write bit enables loop mode operation. In loop mode the RxD pin is disconnected from the SCI, and the transmitter output goes into the receiver input. Both the transmitter and the receiver must be enabled to use loop mode. Reset clears the LOOPS bit.

- 1 = Loop mode enabled
- 0 = Normal operation enabled

ENSCI — Enable SCI Bit

This read/write bit enables the SCI and the SCI baud rate generator. Clearing ENSCI sets the SCTE and TC bits in SCI status register 1 and disables transmitter interrupts. Reset clears the ENSCI bit.

- 1 = SCI enabled
- 0 = SCI disabled

TXINV — Transmit Inversion Bit

This read/write bit reverses the polarity of transmitted data. Reset clears the TXINV bit.

- 1 = Transmitter output inverted
- 0 = Transmitter output not inverted

NOTE

Setting the TXINV bit inverts all transmitted values, including idle, break, start, and stop bits.

9.8.3 SCI Control Register 3

SCI control register 3:

- Stores the ninth SCI data bit received and the ninth SCI data bit to be transmitted
- Enables these interrupts:
 - Receiver overrun interrupts
 - Noise error interrupts
 - Framing error interrupts
- Parity error interrupts

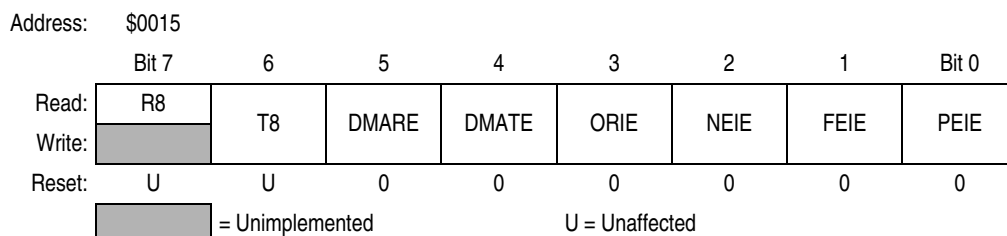


Figure 9-11. SCI Control Register 3 (SCC3)

R8 — Received Bit 8

When the SCI is receiving 9-bit characters, R8 is the read-only ninth bit (bit 8) of the received character. R8 is received at the same time that the SCDR receives the other 8 bits. When the SCI is receiving 8-bit characters, R8 is a copy of the eighth bit (bit 7). Reset has no effect on the R8 bit.

T8 — Transmitted Bit 8

When the SCI is transmitting 9-bit characters, T8 is the read/write ninth bit (bit 8) of the transmitted character. T8 is loaded into the transmit shift register at the same time that the SCDR is loaded into the transmit shift register. Reset has no effect on the T8 bit.

DMARE — DMA Receive Enable Bit

CAUTION

The DMA module is not included on this MCU. Writing a logic 1 to DMARE or DMATE may adversely affect MCU performance.

- 1 = DMA not enabled to service SCI receiver DMA service requests generated by the SCRF bit (SCI receiver CPU interrupt requests enabled)
- 0 = DMA not enabled to service SCI receiver DMA service requests generated by the SCRF bit (SCI receiver CPU interrupt requests enabled)

DMATE — DMA Transfer Enable Bit

CAUTION

The DMA module is not included on this MCU. Writing a logic 1 to DMARE or DMATE may adversely affect MCU performance.

- 1 = SCTE DMA service requests enabled; SCTE CPU interrupt requests disabled
- 0 = SCTE DMA service requests disabled; SCTE CPU interrupt requests enabled

ORIE — Receiver Overrun Interrupt Enable Bit

This read/write bit enables SCI error CPU interrupt requests generated by the receiver overrun bit, OR.

- 1 = SCI error CPU interrupt requests from OR bit enabled
- 0 = SCI error CPU interrupt requests from OR bit disabled

10.3.2 Voltage Conversion

When the input voltage to the ADC equals V_{DD} , the ADC converts the signal to \$FF (full scale). If the input voltage equals V_{SS} , the ADC converts it to \$00. Input voltages between V_{DD} and V_{SS} are a straight-line linear conversion. All other input voltages will result in \$FF if greater than V_{DD} and \$00 if less than V_{SS} .

NOTE

Input voltage should not exceed the analog supply voltages.

10.3.3 Conversion Time

Fourteen ADC internal clocks are required to perform one conversion. The ADC starts a conversion on the first rising edge of the ADC internal clock immediately following a write to the ADSCR. If the ADC internal clock is selected to run at 1 MHz, then one conversion will take 14 μ s to complete. With a 1 MHz ADC internal clock the maximum sample rate is 71.43 kHz.

$$\text{Conversion Time} = \frac{14 \text{ ADC Clock Cycles}}{\text{ADC Clock Frequency}}$$

$$\text{Number of Bus Cycles} = \text{Conversion Time} \times \text{Bus Frequency}$$

10.3.4 Continuous Conversion

In the continuous conversion mode, the ADC continuously converts the selected channel filling the ADC data register with new data after each conversion. Data from the previous conversion will be overwritten whether that data has been read or not. Conversions will continue until the ADCO bit is cleared. The COCO bit (ADC status and control register, \$003C) is set after each conversion and can be cleared by writing the ADC status and control register or reading of the ADC data register.

10.3.5 Accuracy and Precision

The conversion process is monotonic and has no missing codes.

10.4 Interrupts

When the AIEN bit is set, the ADC module is capable of generating a CPU interrupt after each ADC conversion. A CPU interrupt is generated if the COCO bit is at logic 0. The COCO bit is not used as a conversion complete flag when interrupts are enabled.

10.5 Low-Power Modes

The following subsections describe the ADC in low-power modes.

10.5.1 Wait Mode

The ADC continues normal operation during wait mode. Any enabled CPU interrupt request from the ADC can bring the MCU out of wait mode. If the ADC is not required to bring the MCU out of wait mode, power down the ADC by setting the ADCH[4:0] bits in the ADC status and control register to logic 1's before executing the WAIT instruction.

11.3 Port B

Port B is an 8-bit special function port that shares all of its port pins with the analog-to-digital converter (ADC) module, see [Chapter 10](#)

11.3.1 Port B Data Register (PTB)

The port B data register contains a data latch for each of the eight port B pins.

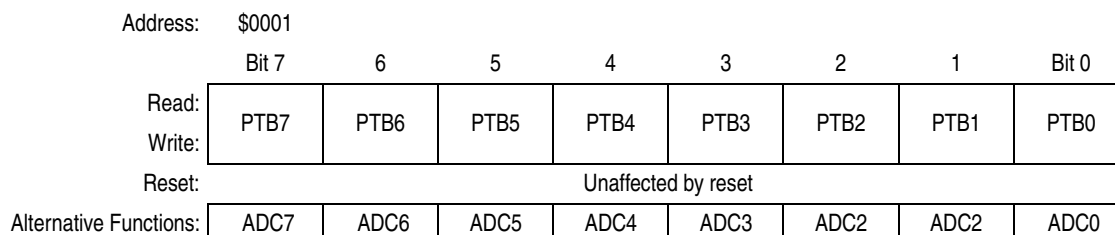


Figure 11-7. Port B Data Register (PTB)

PTB[7:0] — Port B Data Bits

These read/write bits are software programmable. Data direction of each port B pin is under the control of the corresponding bit in data direction register B. Reset has no effect on port B data.

ADC7–ADC0 — ADC channels 7 to 0

ADC7–ADC0 are pins used for the input channels to the analog-to-digital converter module. The channel select bits, ADCH[4:0], in the ADC status and control register define which port pin will be used as an ADC input and overrides any control from the port I/O logic. See [Chapter 10 Analog-to-Digital Converter \(ADC\)](#).

11.3.2 Data Direction Register B (DDRB)

Data direction register B determines whether each port B pin is an input or an output. Writing a logic 1 to a DDRB bit enables the output buffer for the corresponding port B pin; a logic 0 disables the output buffer.

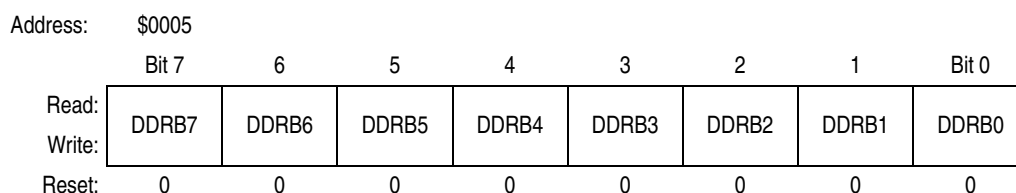


Figure 11-8. Data Direction Register B (DDRB)

DDRB[7:0] — Data Direction Register B Bits

These read/write bits control port B data direction. Reset clears DDRB[7:0], configuring all port B pins as inputs.

1 = Corresponding port B pin configured as output

0 = Corresponding port B pin configured as input

NOTE

Avoid glitches on port B pins by writing to the port B data register before changing data direction register B bits from 0 to 1. [Figure 11-9](#) shows the port B I/O logic.

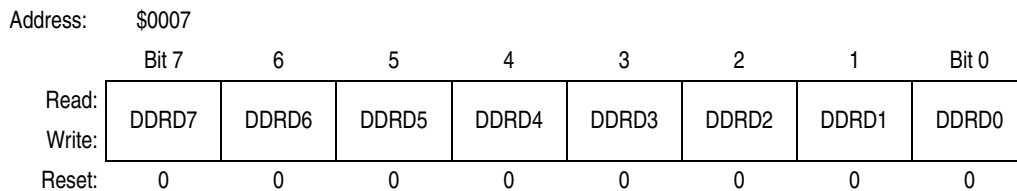


Figure 11-11. Data Direction Register D (DDRD)

DDRD[7:0] — Data Direction Register D Bits

These read/write bits control port D data direction. Reset clears DDRD[7:0], configuring all port D pins as inputs.

- 1 = Corresponding port D pin configured as output
- 0 = Corresponding port D pin configured as input

NOTE

Avoid glitches on port D pins by writing to the port D data register before changing data direction register D bits from 0 to 1. [Figure 11-12](#) shows the port D I/O logic.

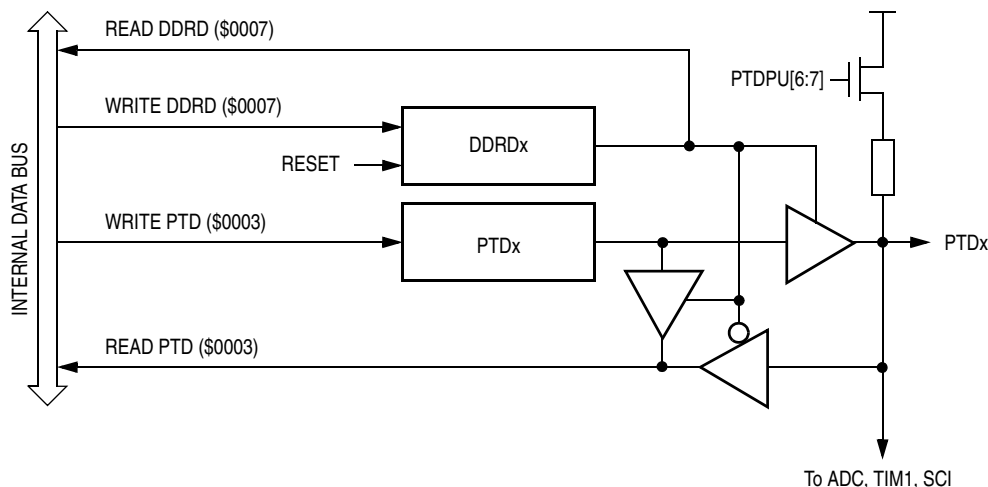


Figure 11-12. Port D I/O Circuit

When DDRDx is a logic 1, reading address \$0003 reads the PTDx data latch. When DDRDx is a logic 0, reading address \$0003 reads the voltage level on the pin. The data latch can always be written, regardless of the state of its data direction bit. [Table 11-4](#) summarizes the operation of the port D pins.

Table 11-4. Port D Pin Functions

DDRD Bit	PTD Bit	I/O Pin Mode	Accesses to DDRD	Accesses to PTD	
			Read/Write	Read	Write
0	X ⁽¹⁾	Input, Hi-Z ⁽²⁾	DDRD[7:0]	Pin	PTD[7:0] ⁽³⁾
1	X	Output	DDRD[7:0]	PTD[7:0]	PTD[7:0]

- 1. X = don't care.
- 2. Hi-Z = high impedance.
- 3. Writing affects data register, but does not affect the input.

18.7 32-Pin Low-Profile Quad Flat Pack (LQFP)

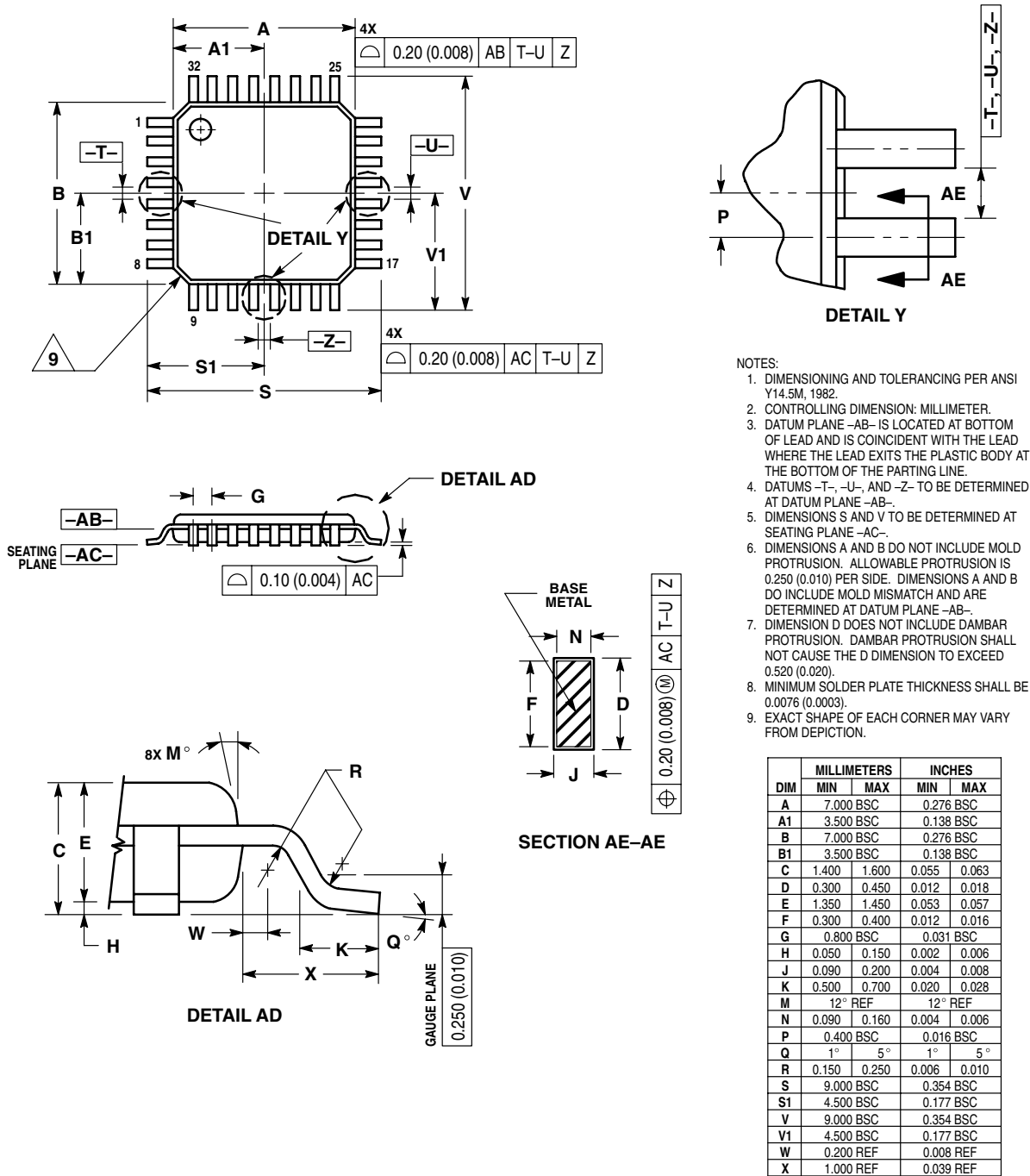


Figure 18-6. 32-Pin LQFP (Case #873A)

B.4 Reserved Registers

The following registers are reserved location on the MC68HC908KL8.

Addr.	Register Name	Bit 7	6	5	4	3	2	1	Bit 0
\$003C	Reserved	Read:	R	R	R	R	R	R	R
		Write:							
		Reset:							
\$003D	Reserved	Read:	R	R	R	R	R	R	R
		Write:							
		Reset:							
\$003E	Reserved	Read:	R	R	R	R	R	R	R
		Write:							
		Reset:							

Figure B-4. Reserved Registers

B.5 Reserved Vectors

The following are reserved interrupt vectors on the MC68HC908KL8.

Table B-2. Reserved Vectors

Vector Priority	INT Flag	Address	Vector
—	IF15	\$FFDE	Reserved
		\$FFDF	Reserved

B.6 MC68HC908KL8 Order Numbers

Table B-3. MC68HC908KL8 Order Numbers

MC Order Number	Operating Temperature Range	Package
MC68HC908KL8CP	–40 °C to +85 °C	28-pin PDIP
MC68HC908KL8CDW	–40 °C to +85 °C	28-pin SOIC
MC68HC908KL8CSP	–40 °C to +85 °C	32-pin SDIP

How to Reach Us:

Home Page:

www.freescale.com

E-mail:

support@freescale.com

USA/Europe or Locations Not Listed:

Freescale Semiconductor
Technical Information Center, CH370
1300 N. Alma School Road
Chandler, Arizona 85224
+1-800-521-6274 or +1-480-768-2130
support@freescale.com

Europe, Middle East, and Africa:

Freescale Halbleiter Deutschland GmbH
Technical Information Center
Schatzbogen 7
81829 Muenchen, Germany
+44 1296 380 456 (English)
+46 8 52200080 (English)
+49 89 92103 559 (German)
+33 1 69 35 48 48 (French)
support@freescale.com

Japan:

Freescale Semiconductor Japan Ltd.
Headquarters
ARCO Tower 15F
1-8-1, Shimo-Meguro, Meguro-ku,
Tokyo 153-0064
Japan
0120 191014 or +81 3 5437 9125
support.japan@freescale.com

Asia/Pacific:

Freescale Semiconductor Hong Kong Ltd.
Technical Information Center
2 Dai King Street
Tai Po Industrial Estate
Tai Po, N.T., Hong Kong
+800 2666 8080
support.asia@freescale.com

For Literature Requests Only:

Freescale Semiconductor Literature Distribution Center
P.O. Box 5405
Denver, Colorado 80217
1-800-441-2447 or 303-675-2140
Fax: 303-675-2150
LDCForFreescaleSemiconductor@hibbertgroup.com

RoHS-compliant and/or Pb-free versions of Freescale products have the functionality and electrical characteristics of their non-RoHS-compliant and/or non-Pb-free counterparts. For further information, see <http://www.freescale.com> or contact your Freescale sales representative.

For information on Freescale's Environmental Products program, go to <http://www.freescale.com/epp>.

Information in this document is provided solely to enable system and software implementers to use Freescale Semiconductor products. There are no express or implied copyright licenses granted hereunder to design or fabricate any integrated circuits or integrated circuits based on the information in this document.

Freescale Semiconductor reserves the right to make changes without further notice to any products herein. Freescale Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Freescale Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters that may be provided in Freescale Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals", must be validated for each customer application by customer's technical experts. Freescale Semiconductor does not convey any license under its patent rights nor the rights of others. Freescale Semiconductor products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Freescale Semiconductor product could create a situation where personal injury or death may occur. Should Buyer purchase or use Freescale Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold Freescale Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Freescale Semiconductor was negligent regarding the design or manufacture of the part.

Freescale™ and the Freescale logo are trademarks of Freescale Semiconductor, Inc. All other product or service names are the property of their respective owners.

© Freescale Semiconductor, Inc. 2005. All rights reserved.